

Fig. 1

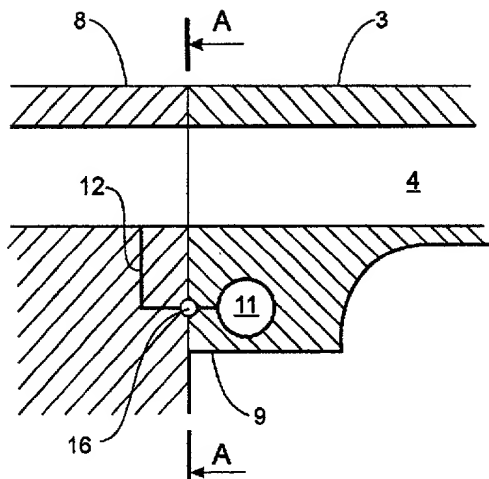


Fig.2A

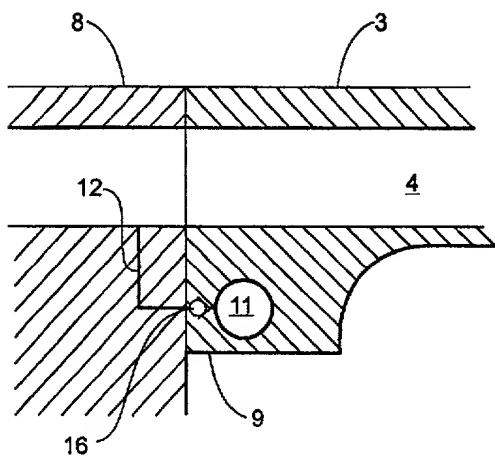


Fig.2B

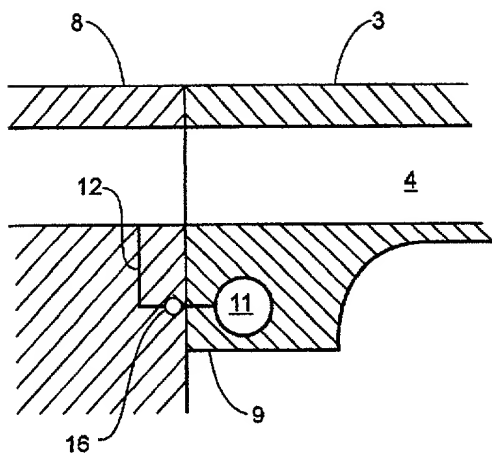


Fig.2C

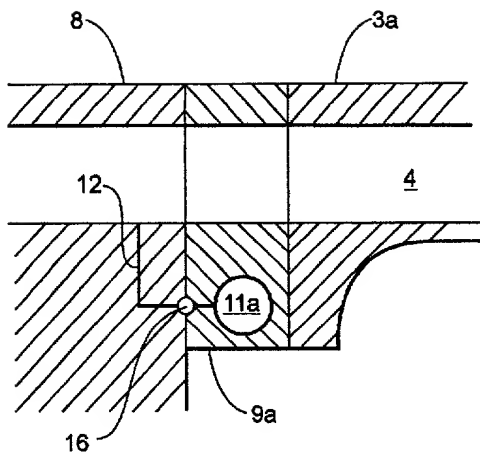


Fig.2D

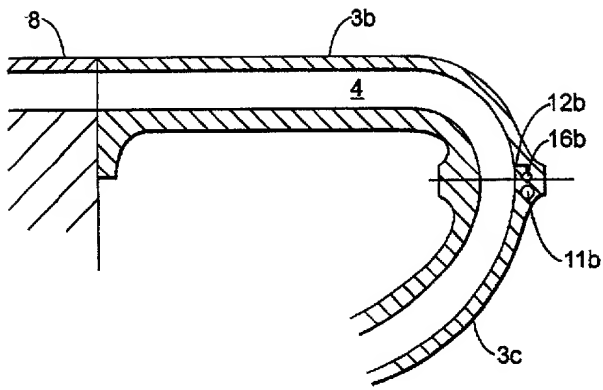


Fig.2E

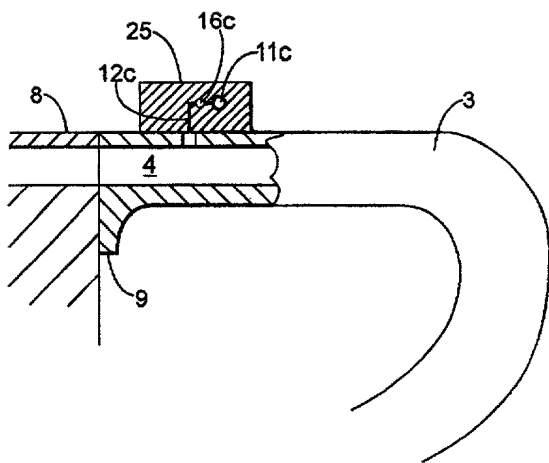


Fig.2F

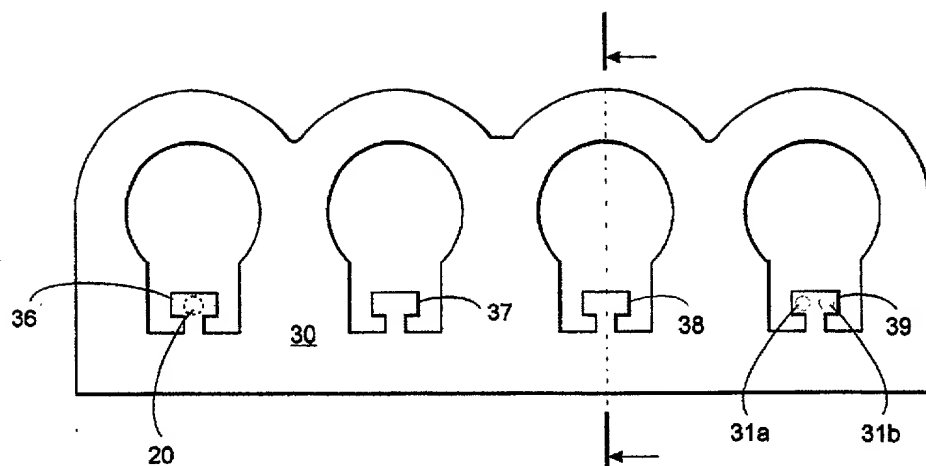


Fig.3A



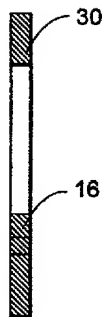


Fig.3B

Fig. 3B is a cross-sectional view of a device 300. The device 300 includes a substrate 310, a first layer 320, a second layer 330, and a third layer 340. The first layer 320 is disposed on the substrate 310, the second layer 330 is disposed on the first layer 320, and the third layer 340 is disposed on the second layer 330. The first layer 320, the second layer 330, and the third layer 340 are disposed in a stacked manner. The first layer 320, the second layer 330, and the third layer 340 are disposed in a stacked manner. The first layer 320, the second layer 330, and the third layer 340 are disposed in a stacked manner.

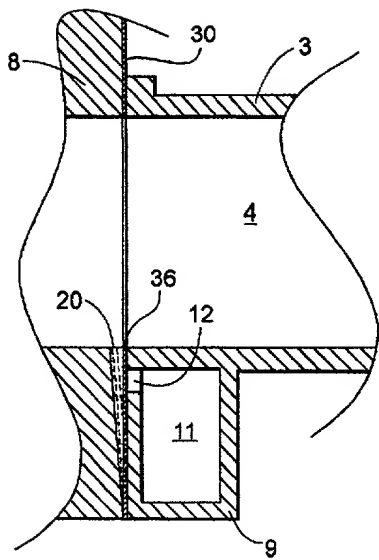


Fig.4

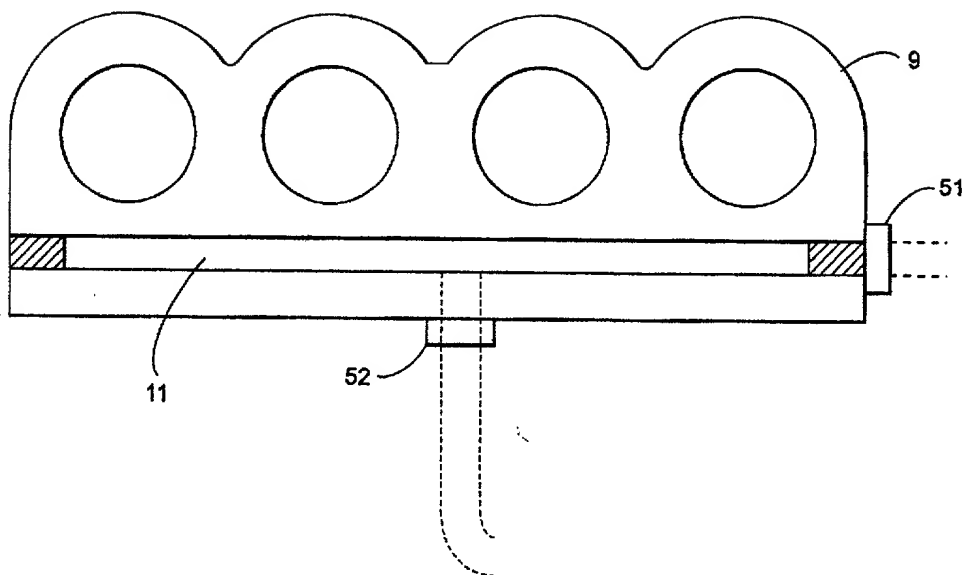


Fig.5

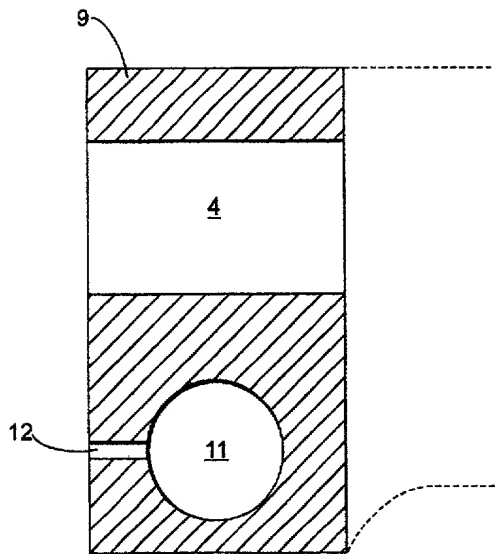


Fig.6A

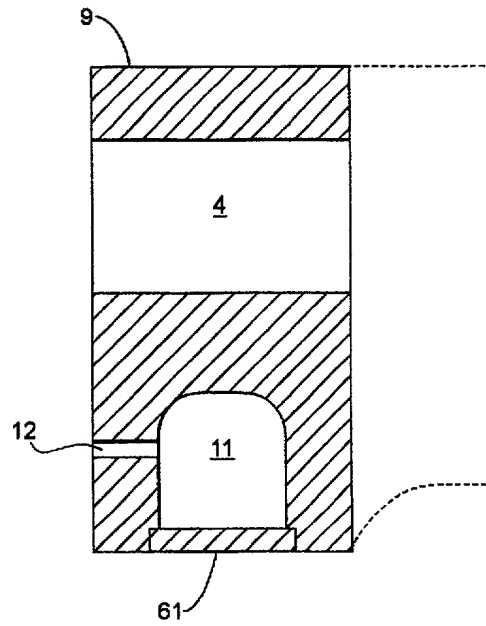


Fig.6B

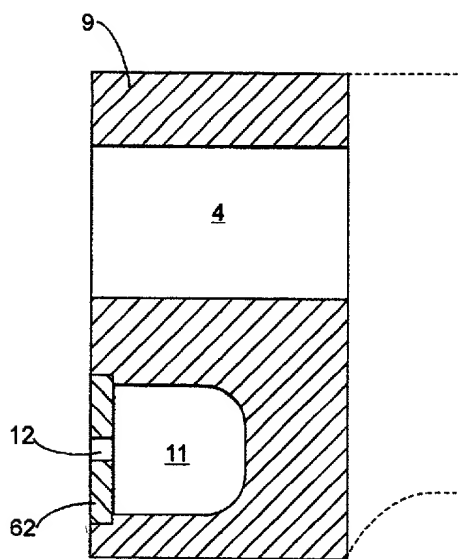


Fig.6C

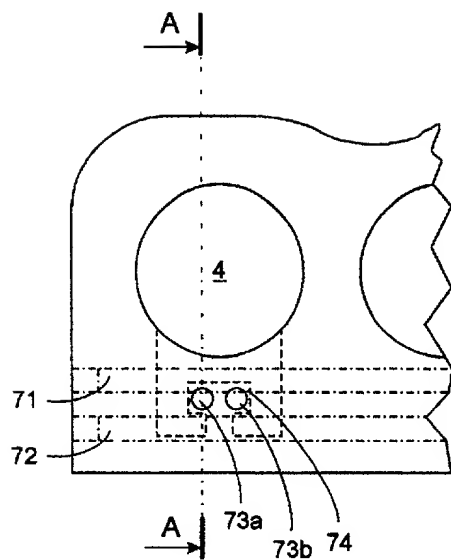


Fig.7A

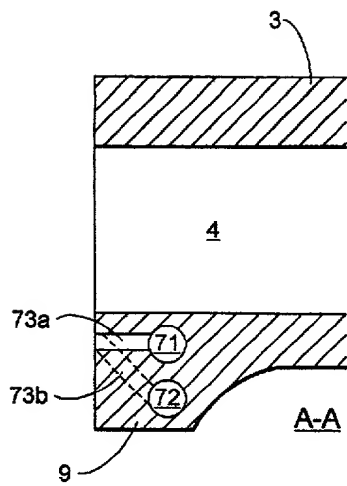


Fig.7B

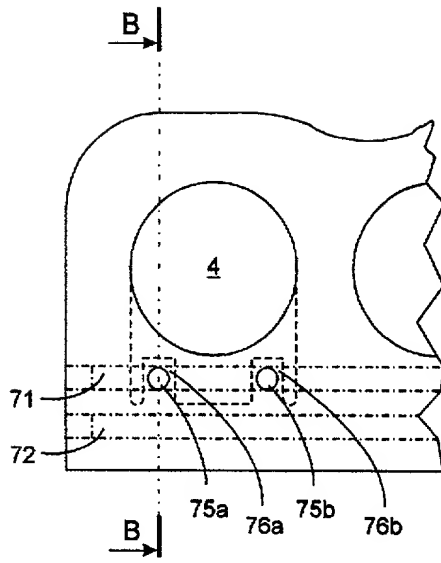


Fig.8A



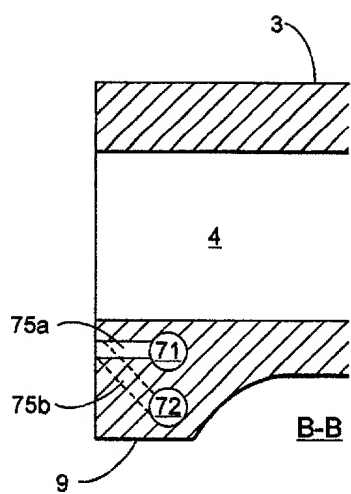


Fig. 8B

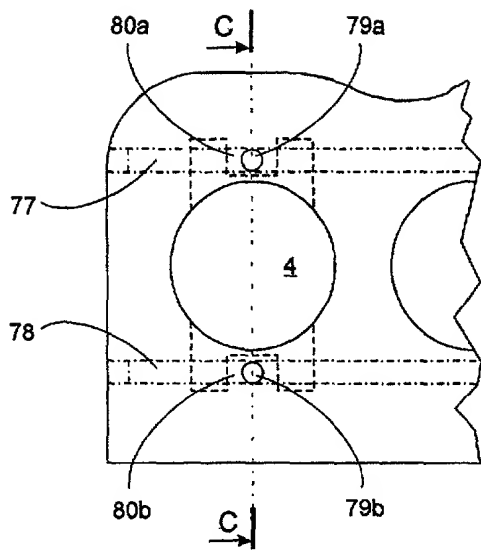


Fig.9A

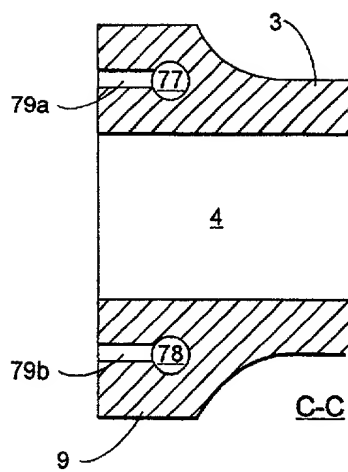


Fig.9B

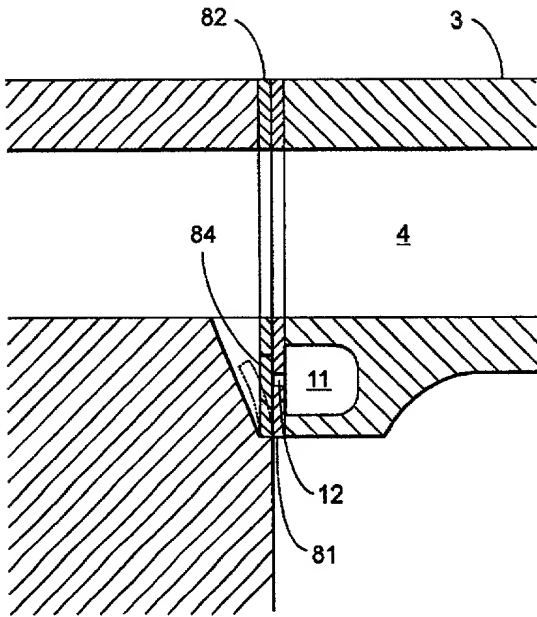


Fig.10A

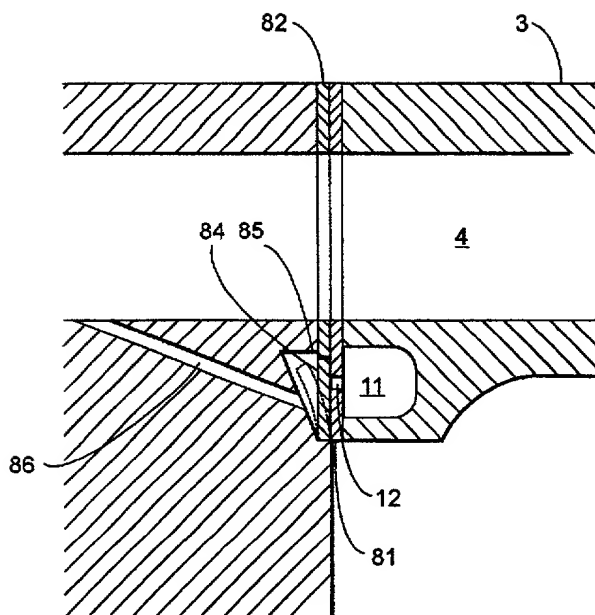


Fig.10B